

MMBD4448

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MMBD4448

250mA Surface Mount Switching Diode- 100V

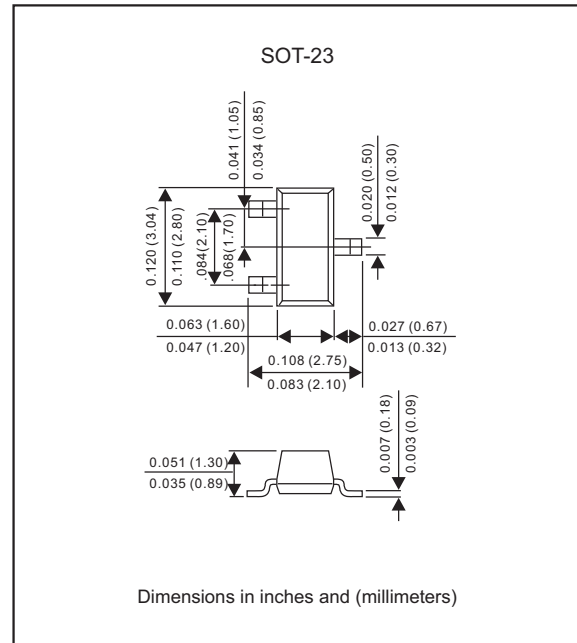
Features

- Fast switching speed
- Surface mount package ideally suited for automatic insertion
- For general purpose switching applications
- High conductance
- Silicon epitaxial planar chip
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free part, ex. MMBD4448-H

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-23
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 0.008 gram

Package Outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Non-repetitive peak reverse voltage	V_{RM}	100	V
Peak repetitive reverse voltage Working peak reverse voltage DC blocking voltage	V_{RRM} V_{RWM} V_R	75	V
RMS reverse voltage	$V_R(RMS)$	53	V
Forward continuous current	I_{FM}	500	mA
Average rectified output current	I_O	250	mA
Non-repetitive peak forward surge current @ $t = 8.3\text{ms}$	I_{FSM}	2.0	A
Total device dissipation, note 1	P_D	350	mW
Typical thermal resistance junction to ambient	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

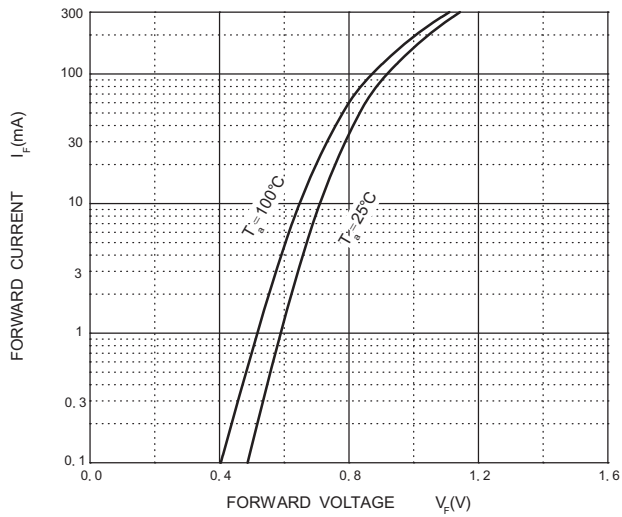
Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	MIN.	TYP.	MAX.	Unit
Forward voltage	$I_F=5\text{mA}$	V_F	0.62		0.72	V
	$I_F=10\text{mA}$				0.855	
	$I_F=100\text{mA}$				1.0	
	$I_F=150\text{mA}$				1.25	
Reverse leakage current	$V_R=75\text{V}$	I_R			2.5	μA
	$V_R=20\text{V}$				25	nA
Capacitance between terminals	$V_R = 0\text{V}$, $f = 1.0\text{MHz}$	C_T			4.0	pF
Reverse recovery time	$I_F = I_R = 10\text{mA}$, $I_{rr} = 0.1 \times I_R$, $R_L = 100\Omega$	t_{rr}			4.0	ns

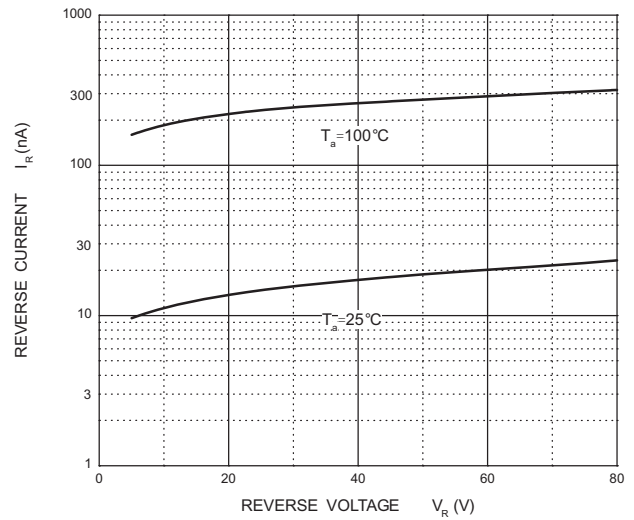
Note 1: Parts Mounted on FR-4 PC Board with recommended pad layout.

Rating and characteristic curves (MMBD4448)

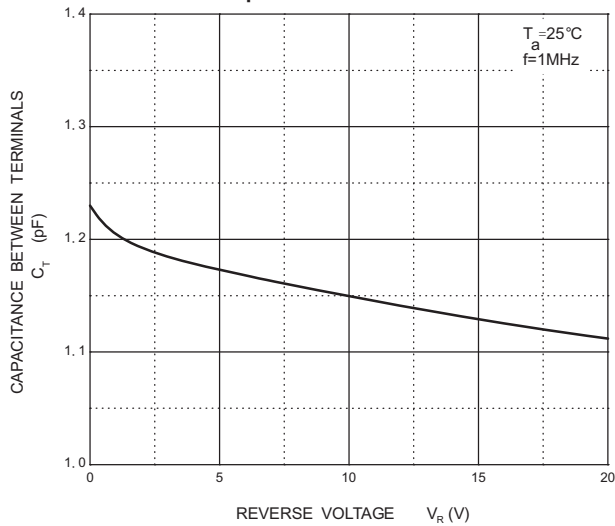
Forward Characteristics



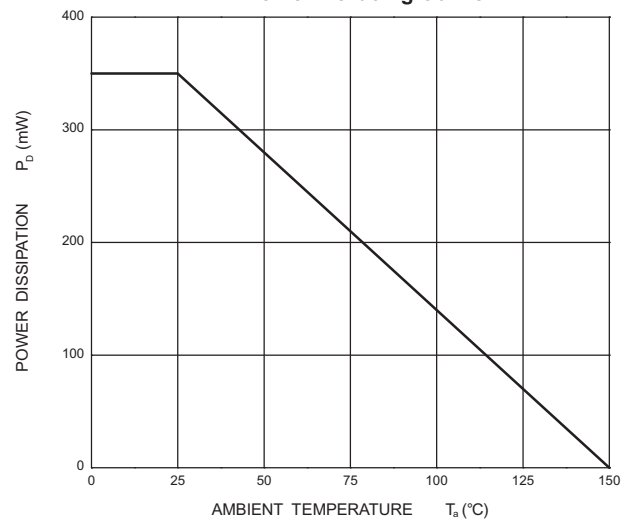
Reverse Characteristics



Capacitance Characteristics

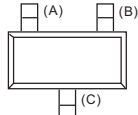
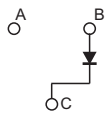


Power Derating Curve



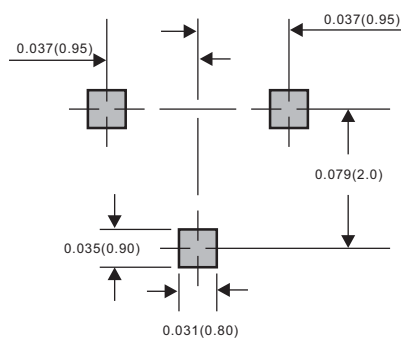
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Pinning information

Type number	Marking code	Simplified outline	Symbol
MMBD4448	KA3		

Suggested solder pad layout

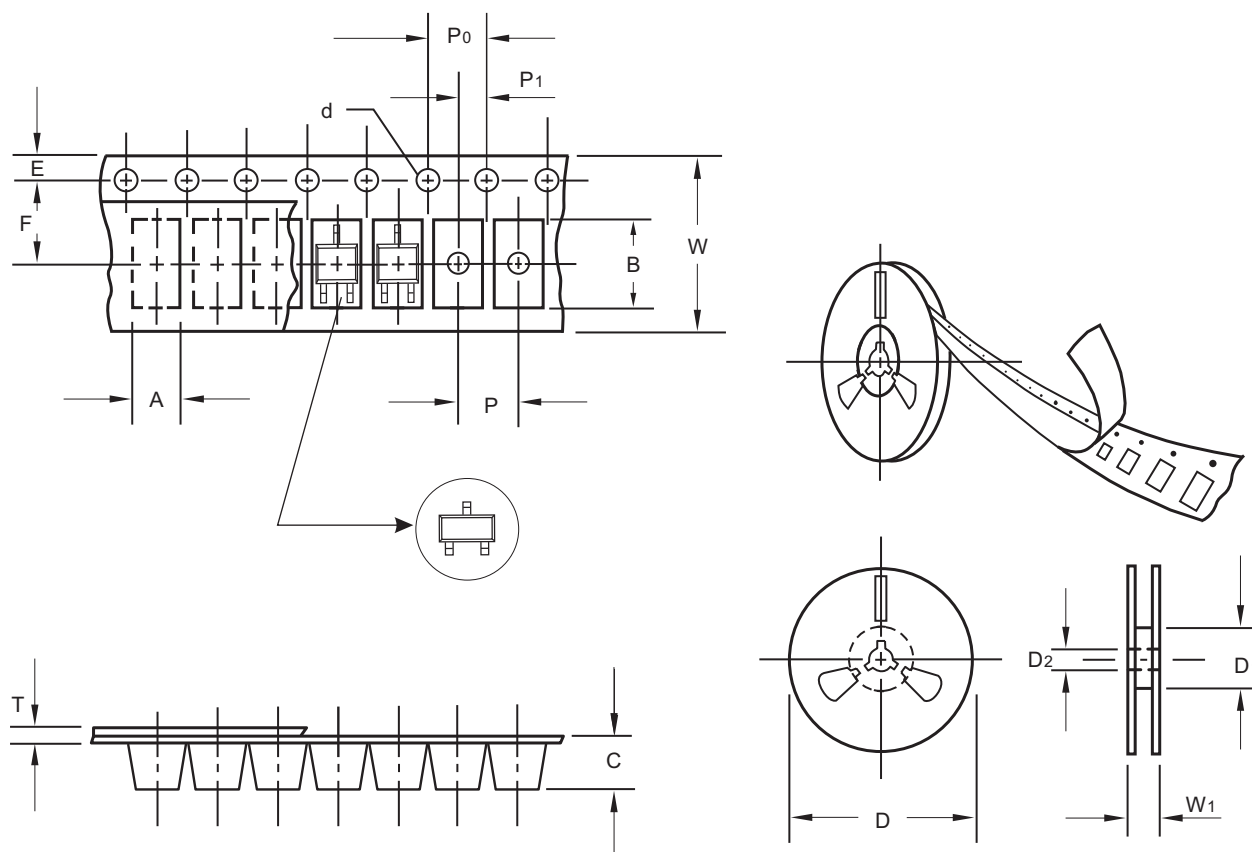
SOT-23



Dimensions in inches and (millimeters)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOT-23
Carrier width	A	0.1	3.15
Carrier length	B	0.1	2.77
Carrier depth	C	0.1	1.22
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

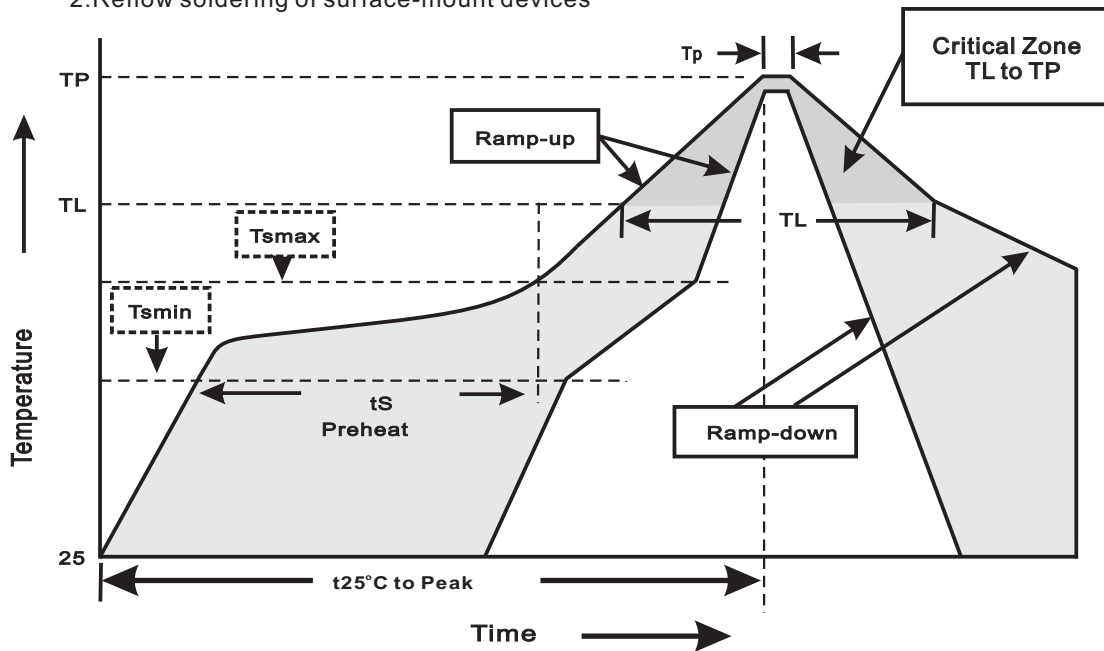
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOT-23	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	11.6

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^\circ\text{C/sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$<3^\circ\text{C/sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^\circ\text{C/sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^{\circ}\text{C}$ for $10 \pm 2\text{sec.}$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	Peak Forward Surge Current	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031